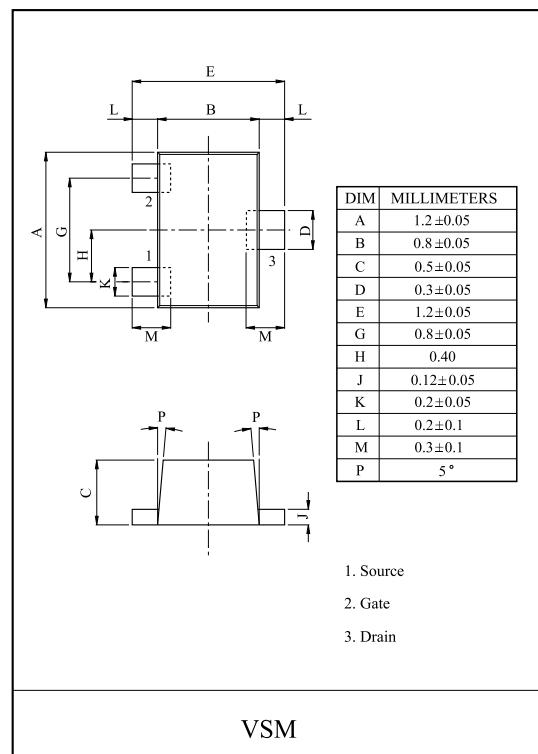


General Description

It's mainly suitable for Load Switching Cell Phones, Battery Powered Systems and Level-Shifter.

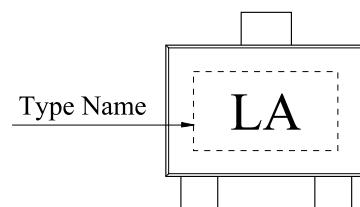
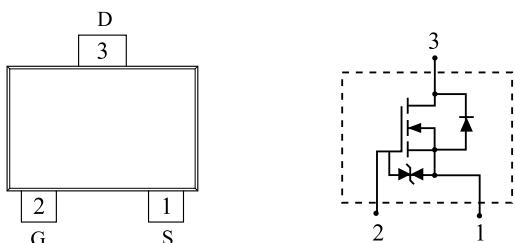
FEATURES

- $V_{DSS}=20V$, $I_D=0.4A$
- Drain-Source ON Resistance
 - : $R_{DS(ON)}=0.70$ @ $V_{GS}=4.5V$
 - : $R_{DS(ON)}=0.85$ @ $V_{GS}=2.5V$
 - : $R_{DS(ON)}=1.25$ @ $V_{GS}=1.8V$
- Super High Dense Cell Design

**MAXIMUM RATING (Ta=25 °C)**

| CHARACTERISTIC | SYMBOL | N-Ch | UNIT |
|------------------------------|---------------|-----------|------|
| Drain-Source Voltage | V_{DSS} | 20 | V |
| Gate-Source Voltage | V_{GSS} | ± 6 | V |
| Drain Current | DC @ $T_A=25$ | I_D^* | 400 |
| | DC @ $T_A=85$ | | 280 |
| | Pulsed | I_{DP} | 650 |
| Source-Drain Diode Current | I_S | 125 | |
| Drain Power Dissipation | P_D^* | 150 | mW |
| Maximum Junction Temperature | T_j | 150 | |
| Storage Temperature Range | T_{stg} | -55 ~ 150 | |

Note 1) *Surface Mounted on 1 × 1 FR4 Board. t = 5 sec

Marking**PIN CONNECTION (TOP VIEW)**

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ELECTRICAL CHARACTERISTICS (Ta=25 °C)

| CHARACTERISTIC | SYMBOL | TEST CONDITION | MIN. | TYP. | MAX. | UNIT |
|------------------------------------|-----------------------|---|------|------|------|------|
| Static | | | | | | |
| Drain-Source Breakdown Voltage | BV _{DSS} | I _D =250 μA, V _{GS} =0V | 20 | - | - | V |
| Drain Cut-off Current | I _{DSS} | V _{GS} =0V, V _{DS} =16V | - | 0.3 | 100 | nA |
| Gate Leakage Current | I _{GSS} | V _{GS} =±4.5V, V _{DS} =0V | - | ±0.5 | ±1.0 | μA |
| Gate Threshold Voltage | V _{th} | V _{DS} =V _{GS} , I _D =250 μA | 0.45 | - | 1.0 | V |
| Drain-Source ON Resistance | R _{DSON} * | V _{GS} =4.5V, I _D =400mA | - | 0.41 | 0.70 | |
| | | V _{GS} =2.5V, I _D =350mA | - | 0.53 | 0.85 | |
| | | V _{GS} =1.8V, I _D =300mA | - | 0.70 | 1.25 | |
| Forward Transconductance | g _{fs} * | V _{DS} =10V, I _D =400mA | - | 1.0 | - | S |
| Source-Drain Diode Forward Voltage | V _{SD} * | I _S =150mA, V _{GS} =0V | - | 0.8 | 1.2 | V |
| Dynamic | | | | | | |
| Total Gate Charge | Q _g * | V _{DS} =10V, I _D =250mA, V _{GS} =4.5V | - | 750 | - | pC |
| Gate-Source Charge | Q _{gs} * | | - | 75 | - | |
| Gate-Drain Charge | Q _{gd} * | | - | 225 | - | |
| Turn-on Delay time | t _{d(on)} * | V _{DD} =10V, I _D =200mA, V _{GS} =4.5V, R _G =10 | - | 5 | - | ns |
| Turn-off Delay time | t _{d(off)} * | | - | 25 | - | |

Note 2) *Pulse test : Pulse width 300μs, Duty Cycle 2%.

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Fig 1. I_D - V_{DS}

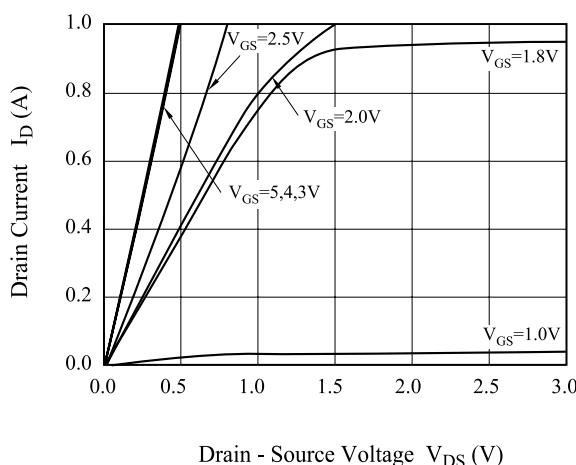


Fig 2. $R_{DS(on)}$ - I_D

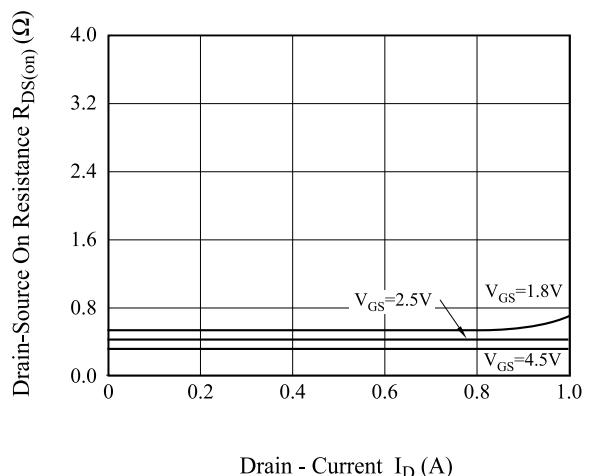


Fig 3. I_D - V_{GS}

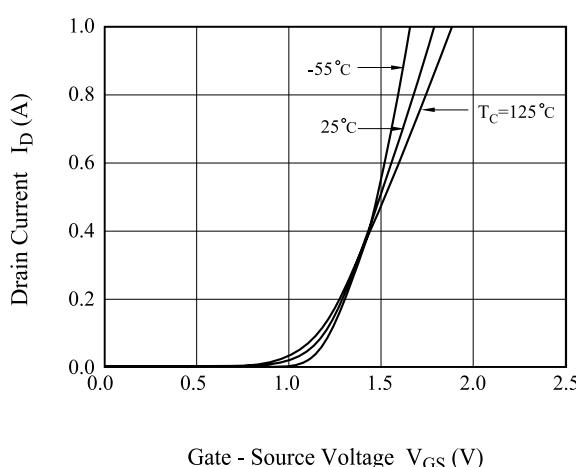


Fig 4. $R_{DS(ON)}$ - T_j

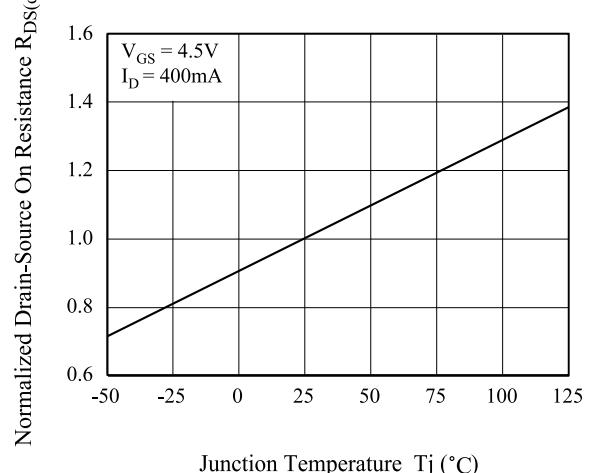


Fig 5. V_{th} - T_j

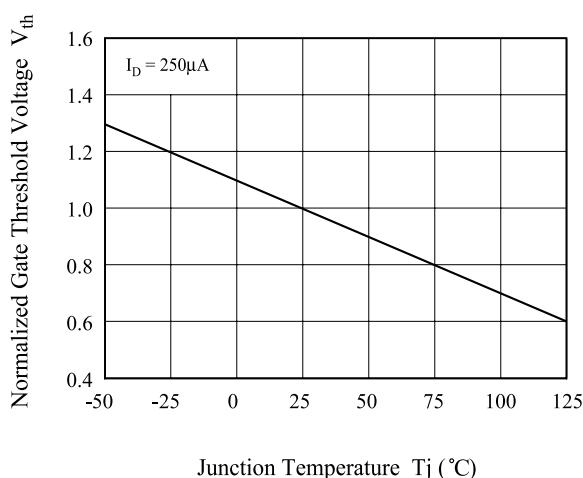
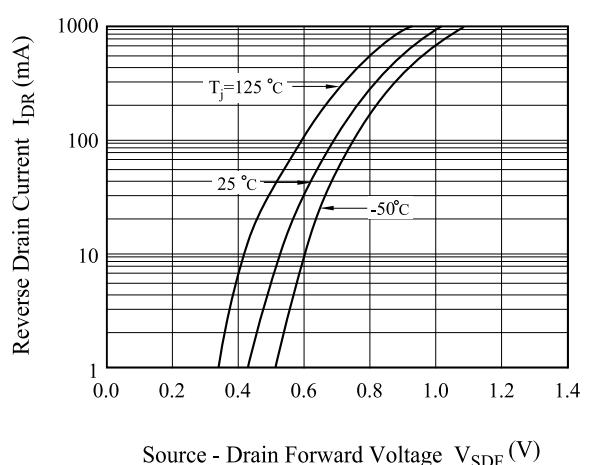


Fig 6. I_{DR} - V_{SDF}



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Fig 7. V_{GS} - Q_g

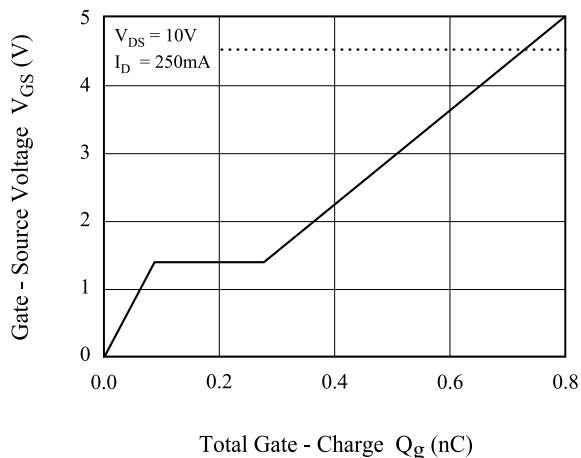
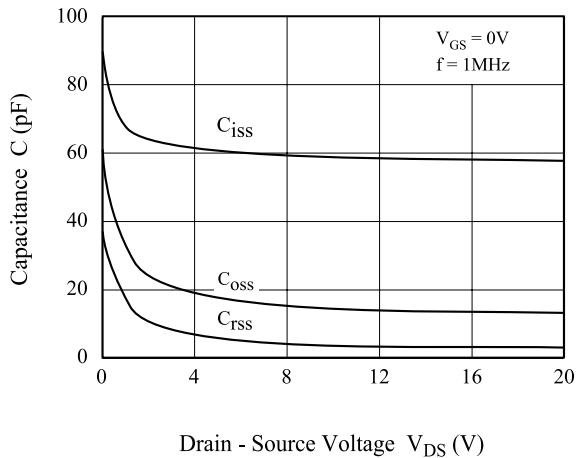


Fig 8. C - V_{DS}



Normalized Effective Transient Thermal Resistance

Fig 9. Transient Thermal Response Curve

